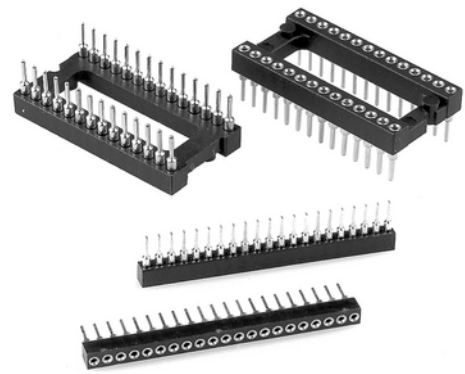


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IC-Fassungen / IC-Leisten RM 1,78mm - Shrink DIP IC Sockets / IC Headers 1.78mm Pitch - Shrink DIP

Technische Daten / Technical Data

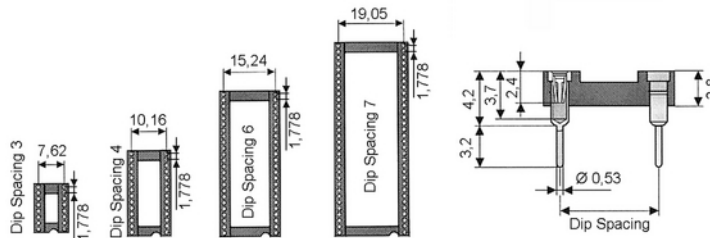
| | |
|---|---|
| Gehäuse/Abdeckung/Hebel <i>Case/Cover/Actuator</i> | Thermoplastischer Kunststoff, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i> |
| Kontaktmaterial | Hülse: Messing gedreht Feder: 4-Lamellen-Clip, Beryllium-Kupfer <i>Sleeve: screw machined brass</i> <i>Clip: 4-Finger-Clip, Beryllium-Copper</i> |
| Contact Material | |
| Kontaktoberfläche <i>Contact Surface</i> | Lt. Oberflächenoptionen, über Ni (2 ... 3µm) <i>Acc. to options (see below), over Ni (2 ... 3µm)</i> |
| Lötbarkeit <i>Solderability</i> | IEC 60512-12A |
| Durchgangswiderstand <i>Contact Resistance</i> | < 10mΩ |
| Isolationswiderstand <i>Insulation Resistance</i> | > 1000MΩ |
| Spannungsfestigkeit <i>Test Voltage</i> | 1kV _{RMS} |
| Nennspannung <i>Voltage Rating</i> | 100V _{RMS} / 150V _{DC} |
| Nennstrom <i>Current Rating</i> | 1A |
| Temperaturbereich <i>Temperature Range</i> | -55°C ... +125°C |
| Verarbeitung <i>Processing</i> | Wellen- oder Reflow-Lötverfahren <i>Wave or reflow soldering</i> |



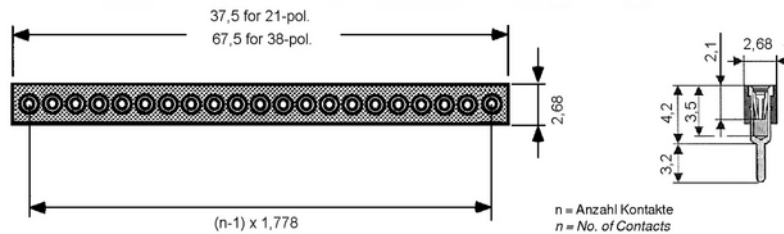
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Für Rundstifte Ø0,40-0,56mm
oder Vierkantstifte 0,25x0,45mm.
For Ø0.40-0.56mm round pins
or 0.25x0.45mm rectangular pins.

IC-Fassung Serie 326 IC-Socket Series 326



IC-Leiste Serie 327 IC-Strip Series 327



| Series | Contacts* | DIP-Spacing* | Sleeve Plating | Clip Plating* |
|-----------------------------|--|---|---|---|
| 326 | 16 | 3 | 50 | 00 |
| 326 IC-Fassung IC-Socket | 16 =====> 28/30/32/48 =====> 20/24/28/40/42/48/ 50/52/56/64/68=====> 64 =====> | 3 7,62mm 4 10,16mm 6 15,24mm 7 19,05mm | 50 Verzinkt (Standard) Tin plated (Standard) | 00 Vergoldet (Standard) Gold plated (Standard) 10 Vergoldet 0,25µm 0,25µm gold plated 30 Vergoldet 0,75µm 0,75µm gold plated |

| Series | Contacts* | Rows | Sleeve Plating | Clip Plating* |
|----------------------------|-------------------------------|---------------------------|---|--|
| 327 | 21 | 1 | 50 | 00 |
| 327 IC-Leiste IC Header | 21/38 Einreihig Single row | 1 Einreihig Single row | 50 Verzinkt (Standard) Tin plated (Standard) | 00 Vergoldet Gold plated 10 Vergoldet 0,25µm 0,25µm gold plated |

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

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Informationen zum Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung

Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

| Profileigenschaft | Kennwert |
|--------------------------------------|--------------|
| Temperatur Minimum T_{Smin} | 150°C |
| Temperatur Maximum T_{Smax} | 200°C |
| Dauer $T_{Smin} - T_{Smax}$ | 60-180s |
| Temperatur Lötbereich T_L | 217°C |
| Verweildauer oberhalb T_L | 60-180s |
| Ramp-Up Rate $T_{Smax} - T_P$ | max. 3°C / s |
| Höchsttemperatur T_P | 260°C ±5 |
| Dauer Höchsttemperatur | 20-40s |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6°C / s |
| Dauer 25°C - Höchsttemperatur T_P | Max. 8 min |

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

| Profile Feature | Key Values |
|--------------------------------------|--------------|
| Minimum Temperature T_{Smin} | 150°C |
| Maximum Temperatur T_{Smax} | 200°C |
| Duration $T_{Smin} - T_{Smax}$ | 60-180s |
| Soldering Range Temperature T_L | 217°C |
| Duration above T_L | 60-180s |
| Ramp-Up Rate $T_{Smax} - T_P$ | max. 3°C / s |
| Peak Temperature T_P | 260°C ±5 |
| Duration Peak Temperature | 20-40s |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6°C / s |
| Duration 25°C - Peak Temp. T_P | Max. 8min |

